



Device Type: 5QX TDFN-8-2x3x0.8mm-NiPdAu						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	4.75	(mg) Total	Leadframe	% of Total Weight	34.05
Silicon	7440-21-3	Die	4.011	0.560	40,107		Copper	7440-50-8	96.1	
Copper	7440-50-8	Leadframe	32.731	4.570	327,308		Zinc	7440-66-6	0.123	
Zinc	7440-66-6	Leadframe	0.042	0.006	419		Ferrous	7439-89-6	2.32	
Ferrous	7439-89-6	Leadframe	0.789	0.110	7,890		Phosphorus	7723-14-0	0.08	
Phosphorus	7723-14-0	Leadframe	0.028	0.004	276		Nickel	7440-02-0	1.28	
Nickel	7440-02-0	Leadframe	0.436	0.061	4,357		Palladium	7440-05-3	0.05	
Palladium	7440-05-3	Leadframe	0.017	0.002	167		Gold	7440-57-5	0.03	
Gold	7440-57-5	Leadframe	0.010	0.001	100	Total				100.00
Silver	7440-22-4	Die Attach	0.985	0.138	9,848					
exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	Die Attach	0.180	0.025	1,797	0.17	(mg) Total	Die Attach	% of Total Weight	1.20
1,1'-(1,3-phenylene)bis-1H-pyrrole-2,5-dione	3006-93-7	Die Attach	0.021	0.003	210		Silver	7440-22-4	82.2	
A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxyp	Proprietary	Die Attach	0.006	0.001	60		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	15.00	
2-(3,4-Epoxycyclohexyl)ethyltrimethoxysilane	3388-04-3	Die Attach	0.006	0.001	60		1,1'-(1,3-phenylene)bis-1H-pyrrole-2,5-dione	3006-93-7	1.75	
2-Methylhydroquinone	95-71-6	Die Attach	0.001	0.000	6		A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxyp	Proprietary	0.50	
Gold	7440-57-5	Bonding Wire	0.775	0.108	7,749		2-(3,4-Epoxycyclohexyl)ethyltrimethoxysilane	3388-04-3	0.50	
Epoxy Resin	Trade Secret	Molding Compound	1.499	0.209	14,991		2-Methylhydroquinone	95-71-6	0.05	
Phenol Resin	Trade Secret	Molding Compound	1.499	0.209	14,991	Total				100.00
Silica (Amorphous)A	60676-86-0	Molding Compound	47.972	6.698	479,717					
Silica (Amorphous)B	7631-86-9	Molding Compound	8.935	1.248	89,347	0.56	(mg) Total	Die	% of Total Weight	4.01
Carbon Black	1333-86-4	Molding Compound	0.060	0.008	600		Silicon	7440-21-3	100.00	
TOTALS: 13.96 mg Total Mass			100.00	13.96	1,000,000	Total				100.00
						0.11	Total (mg)	Bonding Wire	% of Total Weight	0.77
							Gold	7440-57-5	100.00	
						Total				100.00
						8.37	(mg) Total	Molding Compound	% of Total Weight	59.96
							Epoxy Resin	Trade Secret	2.50	
							Phenol Resin	Trade Secret	2.50	
							Silica (Amorphous)A	60676-86-0	80.00	
							Silica (Amorphous)B	7631-86-9	14.90	
							Carbon Black	1333-86-4	0.10	
						13.96	Total	Total	100.00	100.00

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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